



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	BGM 13HBA12 E6327	<b>Issued</b>	22. April 2022
<b>MA#</b>	MA005709561		
<b>Package</b>	PG-ATSLP-12-13	<b>Weight*</b>	2.29 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.452	19.76	19.76	197571	197571
bumps	non noble metal	copper	7440-50-8	0.022	0.94	0.94	9427	9427
encapsulation	organic material	carbon black	1333-86-4	0.006	0.26		2599	
	inorganic material	zink oxide	1314-13-2	0.012	0.52		5198	
	miscellaneous	miscellaneous	-	0.018	0.78		7798	
	plastics	epoxy resin	-	0.131	5.72		57181	
	inorganic material	silicondioxide	60676-86-0	1.023	44.69	51.97	447054	519830
leadfinish	noble metal	gold	7440-57-5	0.034	1.47		14745	
	non noble metal	nickel	7440-02-0	0.038	1.68	3.15	16817	31562
solder	noble metal	silver	7440-22-4	0.000	0.01		62	
	non noble metal	tin	7440-31-5	0.008	0.34	0.35	3358	3420
ubm	non noble metal	titanium	7440-32-6	0.000			11	
	non noble metal	copper	7440-50-8	0.000	0.01	0.01	90	101
solder resists	inorganic material	silicondioxide	60676-86-0	0.005	0.22		2160	
	inorganic material	bariumsulfate	7727-43-7	0.005	0.22		2185	
	plastics	acrylic resin	-	0.013	0.58	1.02	5818	10163
substrate metal	non noble metal	copper	7440-50-8	0.315	13.76	13.76	137605	137605
substrate plastic	organic material	carbon black	1333-86-4	0.001	0.03		271	
	plastics	epoxy resin	-	0.024	1.06		10568	
	inorganic material	silicondioxide	60676-86-0	0.182	7.95	9.04	79482	90321
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

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